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FQP50N06

60V N-Channel MOSFET

General Description

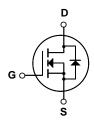
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as automotive, DC/ DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- 50A, 60V, $R_{DS(on)}$ = 0.022 Ω @V_{GS} = 10 V Low gate charge (typical 31 nC)
- Low Crss (typical 65 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQP50N06	Units
V _{DSS}	Drain-Source Voltage		60	V
I _D	Drain Current - Continuous (T _C = 25°C)		50	А
	- Continuous (T _C = 100°C)		35.4	А
I _{DM}	Drain Current - Pulsed	(Note 1)	200	А
V _{GSS}	Gate-Source Voltage		± 25	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	490	mJ
I _{AR}	Avalanche Current	(Note 1)	50	А
E _{AR}	Repetitive Avalanche Energy	(Note 1)	12	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	7.0	V/ns
P_{D}	Power Dissipation (T _C = 25°C)		120	W
	- Derate above 25°C		0.8	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.24	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°	С	0.06		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60 V, V _{GS} = 0 V			1	μА
		V _{DS} = 48 V, T _C = 150°C			10	μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}$		0.018	0.022	Ω
g _{FS}	Forward Transconductance	V _{DS} = 25 V, I _D = 25 A (Note	4)	22		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		1180 440 65	1540 580 90	pF pF
	ing Characteristics					μ.
t _{d(on)}	Turn-On Delay Time	V 20 V I 25 A		15	40	ns
t _r	Turn-On Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 25 \text{ A},$ $R_{G} = 25 \Omega$		105	220	ns
t _{d(off)}	Turn-Off Delay Time	NG - 23 32		60	130	ns
t _f	Turn-Off Fall Time	(Note 4,	5)	65	140	ns
Qg	Total Gate Charge	V _{DS} = 48 V, I _D = 50 A,		31	41	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		8		nC
Q _{gd}	Gate-Drain Charge	(Note 4,	5)	13		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
Is	Maximum Continuous Drain-Source Diode Forward Current				50	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F				200	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 50 \text{ A}$			1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 50 \text{ A,}$		52		ns
Q _{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note	4)	75		nC

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 230μH, I_{AS} = 50A, V_{DD} = 25V, R_G = 25 Ω, Starting T_J = 25°C 3. lg_D = 50A, di/dt \leq 300A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

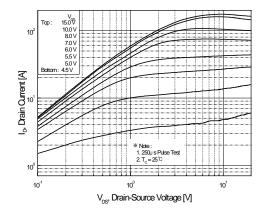


Figure 1. On-Region Characteristics

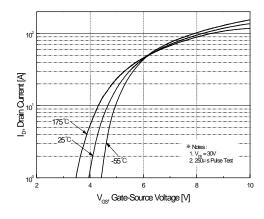


Figure 2. Transfer Characteristics

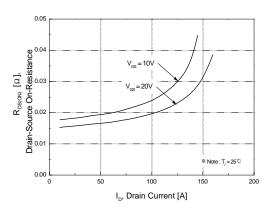


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

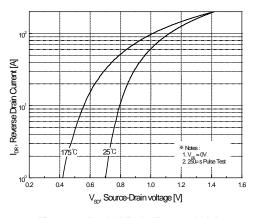


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

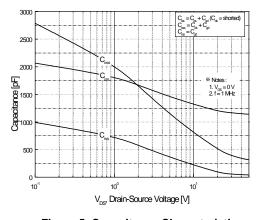


Figure 5. Capacitance Characteristics

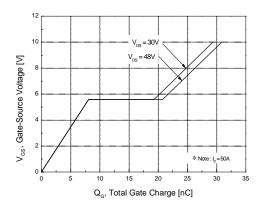


Figure 6. Gate Charge Characteristics

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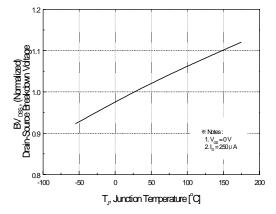


Figure 7. Breakdown Voltage Variation vs. Temperature

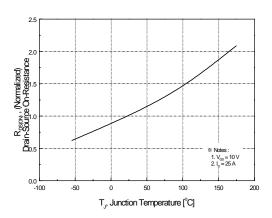


Figure 8. On-Resistance Variation vs. Temperature

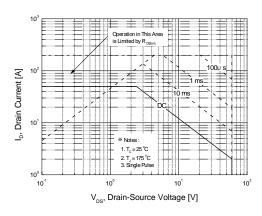


Figure 9. Maximum Safe Operating Area

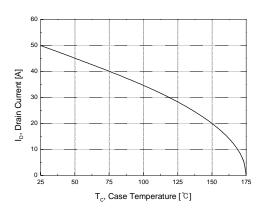


Figure 10. Maximum Drain Current vs. Case Temperature

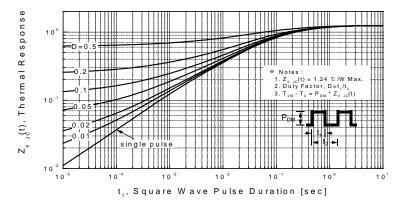
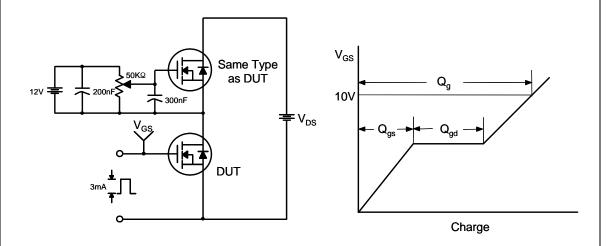


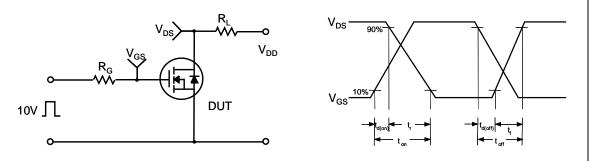
Figure 11. Transient Thermal Response Curve

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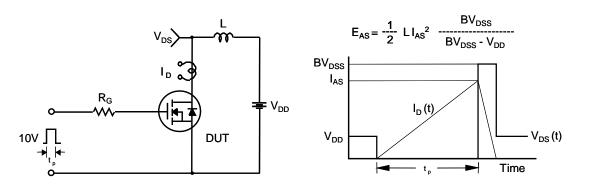
Gate Charge Test Circuit & Waveform



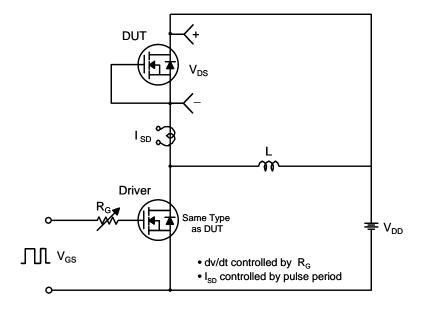
Resistive Switching Test Circuit & Waveforms

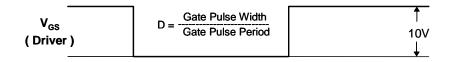


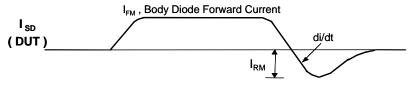
Unclamped Inductive Switching Test Circuit & Waveforms



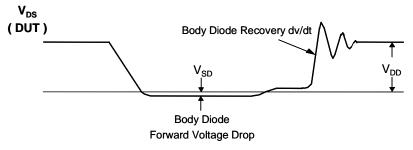
Peak Diode Recovery dv/dt Test Circuit & Waveforms

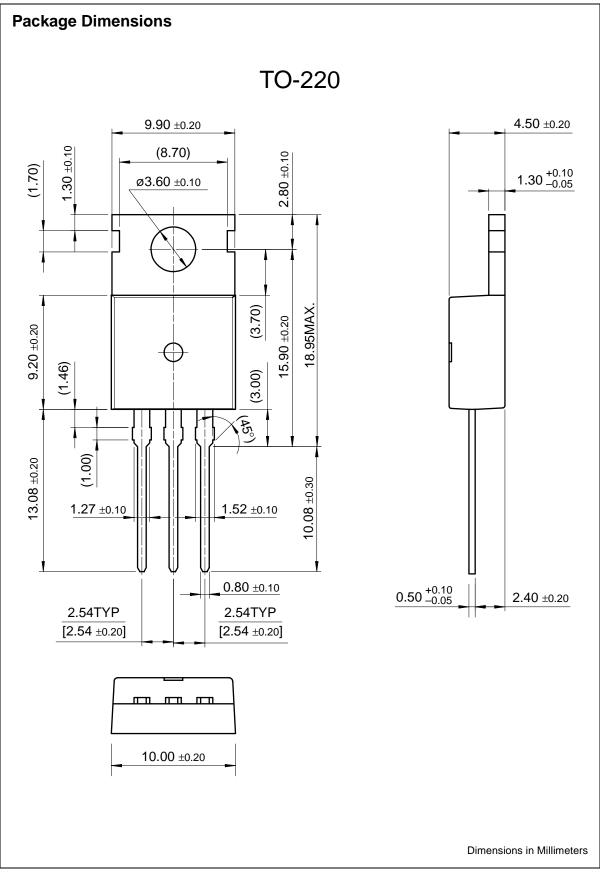






Body Diode Reverse Current





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